

CSD19506KCS 80V N-Channel NexFET™ Power MOSFET

1 Features

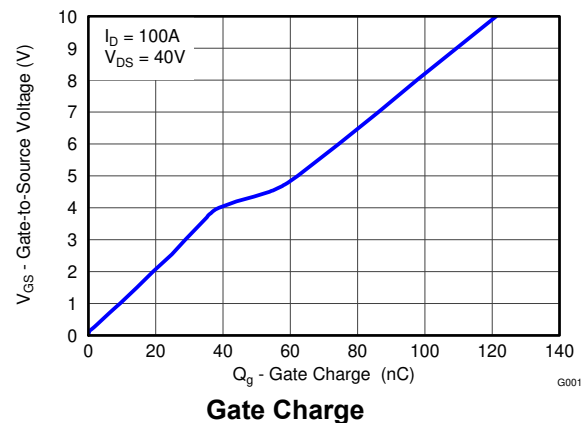
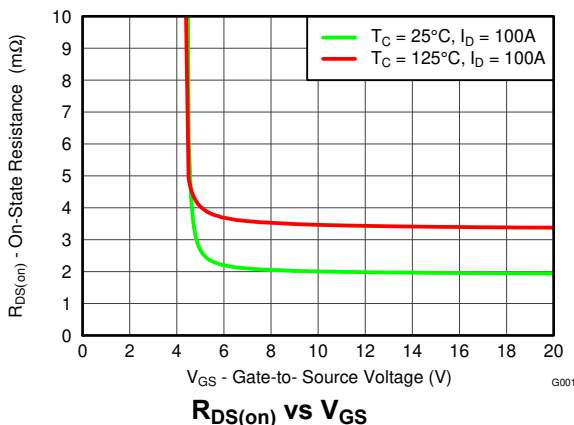
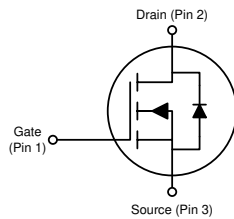
- Ultra-low Q_g and Q_{gd}
- Low thermal resistance
- Avalanche rated
- Pb-free terminal plating
- RoHS compliant
- Halogen free
- TO-220 plastic package

2 Applications

- Secondary side synchronous rectifier
- Motor control

3 Description

This 80V, 2.0m Ω , TO-220 NexFET™ power MOSFET is designed to minimize losses in power conversion applications.



Product Summary

$T_A = 25^\circ\text{C}$		TYPICAL VALUE		UNIT
V_{DS}	Drain-to-Source Voltage	80		V
Q_g	Gate Charge Total (10V)	120		nC
Q_{gd}	Gate Charge Gate to Drain	20		nC
$R_{DS(on)}$	Drain-to-Source On Resistance	$V_{GS} = 6\text{V}$	2.2	m Ω
		$V_{GS} = 10\text{V}$	2.0	m Ω
$V_{GS(th)}$	Threshold Voltage	2.5		V

Ordering Information

Device	Package ⁽¹⁾	Media	Qty	Ship
CSD19506KCS	TO-220 Plastic Package	Tube	50	Tube

- (1) For all available packages, see the orderable addendum at the end of the data sheet.

Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage	80	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current (Package limited)	150	A
	Continuous Drain Current (Silicon limited), $T_C = 25^\circ\text{C}$	273	
	Continuous Drain Current (Silicon limited), $T_C = 100^\circ\text{C}$	193	
I_{DM}	Pulsed Drain Current ⁽¹⁾	400	A
P_D	Power Dissipation	375	W
T_J , T_{stg}	Operating Junction and Storage Temperature Range	-55 to 175	$^\circ\text{C}$
E_{AS}	Avalanche Energy, single pulse $I_D = 129\text{A}$, $L = 0.1\text{mH}$, $R_G = 25\Omega$	832	mJ

- (1) Max $R_{\theta JC} = 0.4^\circ\text{C/W}$, pulse duration $\leq 100\mu\text{s}$, duty cycle $\leq 1\%$



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4 Specifications

4.1 Electrical Characteristics

(T_A = 25°C unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
BV _{DSS}	Drain-to-Source Voltage	V _{GS} = 0V, I _D = 250μA	80			V
I _{DSS}	Drain-to-Source Leakage Current	V _{GS} = 0V, V _{DS} = 64V			1	μA
I _{GSS}	Gate-to-Source Leakage Current	V _{DS} = 0V, V _{GS} = 20V			100	nA
V _{GS(th)}	Gate-to-Source Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.1	2.5	3.2	V
R _{DS(on)}	Drain-to-Source On-Resistance	V _{GS} = 6V, I _D = 100A			2.2	mΩ
		V _{GS} = 10V, I _D = 100A			2.0	mΩ
g _{fs}	Transconductance	V _{DS} = 8V, I _D = 100A	297			S
DYNAMIC CHARACTERISTICS						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 40V, f = 1MHz		9380	12200	pF
C _{oss}	Output Capacitance			2260	2940	pF
C _{rss}	Reverse Transfer Capacitance			42	55	pF
R _G	Series Gate Resistance	V _{DS} = 40V, I _D = 100A		1.3	2.6	Ω
Q _g	Gate Charge Total (10V)			120	156	nC
Q _{gd}	Gate Charge Gate to Drain			20		nC
Q _{gs}	Gate Charge Gate to Source			37		nC
Q _{g(th)}	Gate Charge at V _{th}			25		nC
Q _{oss}	Output Charge	V _{DS} = 40V, V _{GS} = 0V		345		nC
t _{d(on)}	Turn On Delay Time	V _{DS} = 40V, V _{GS} = 10V, I _{DS} = 100A, R _G = 0Ω		19		ns
t _r	Rise Time			11		ns
t _{d(off)}	Turn Off Delay Time			30		ns
t _f	Fall Time			10		ns
DIODE CHARACTERISTICS						
V _{SD}	Diode Forward Voltage	I _{SD} = 100A, V _{GS} = 0V		0.9	1.1	V
Q _{rr}	Reverse Recovery Charge	V _{DS} = 40V, I _F = 100A, di/dt = 300A/μs		525		nC
t _{rr}	Reverse Recovery Time			107		ns

4.2 Thermal Information

(T_A = 25°C unless otherwise stated)⁽¹⁾

THERMAL METRIC		MIN	TYP	MAX	UNIT
R _{θJC}	Junction-to-Case Thermal Resistance			0.4	°C/W
R _{θJA}	Junction-to-Ambient Thermal Resistance			62	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

4.3 Typical MOSFET Characteristics

($T_A = 25^\circ\text{C}$ unless otherwise stated)

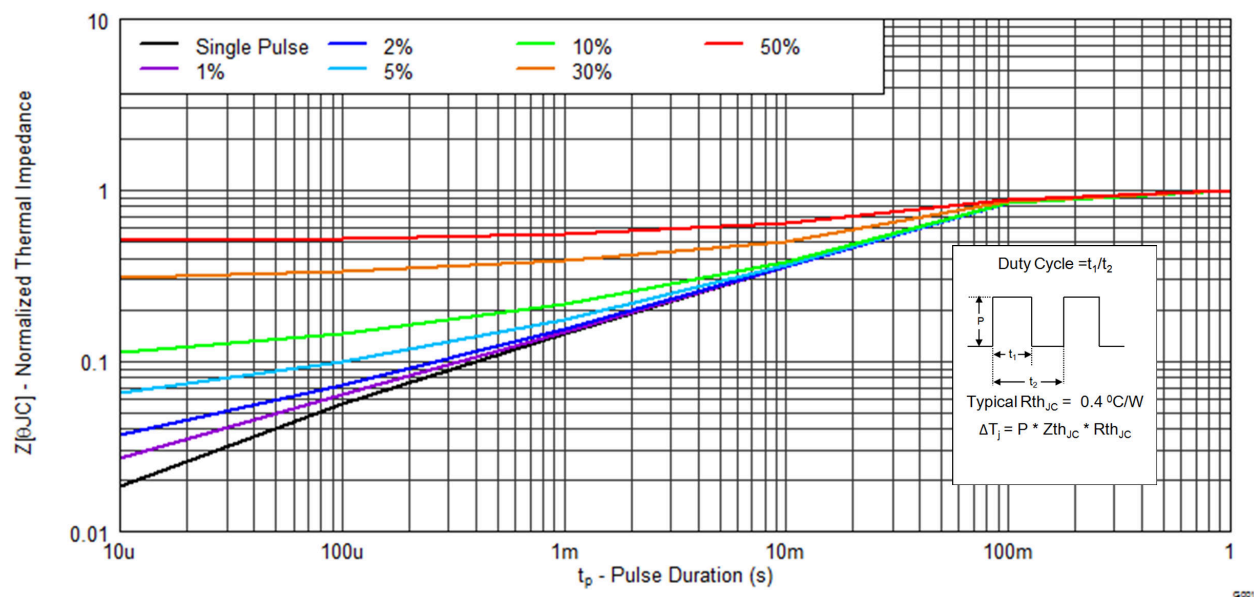


Figure 4-1. Transient Thermal Impedance

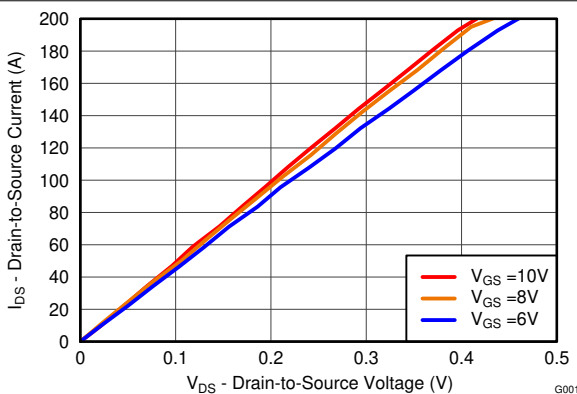


Figure 4-2. Saturation Characteristics

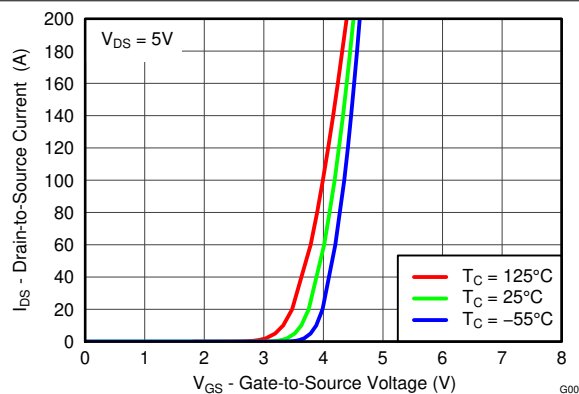
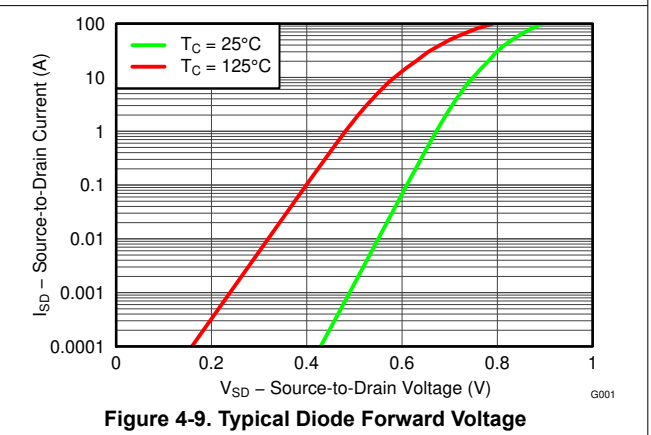
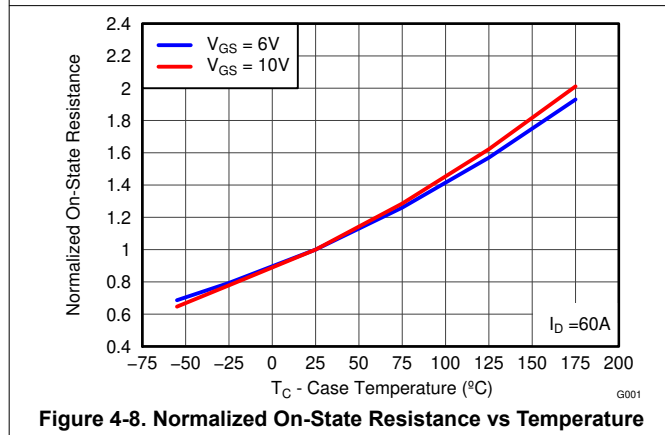
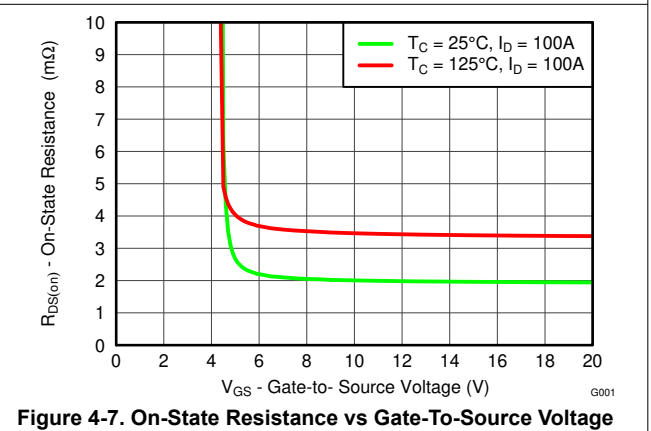
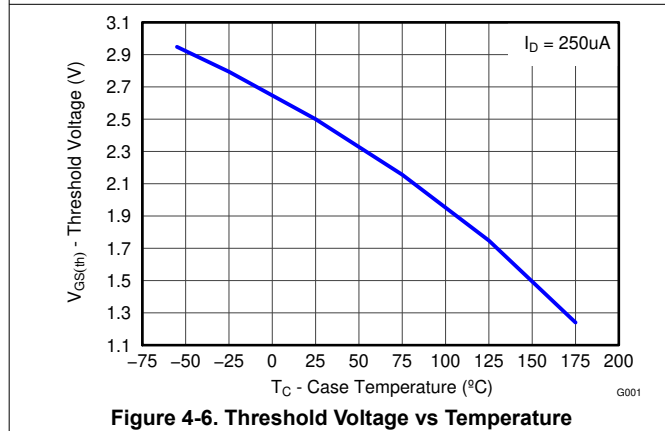
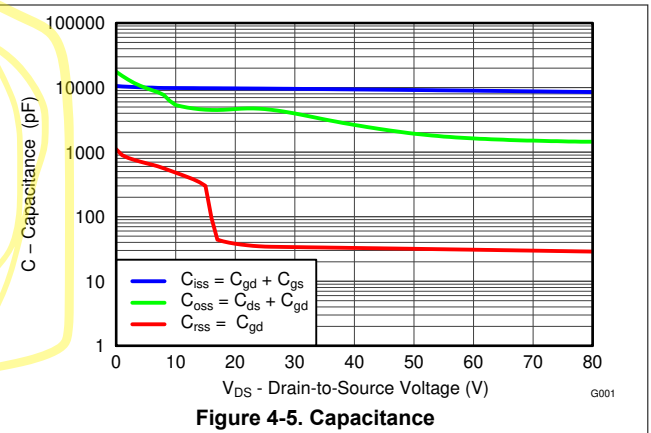
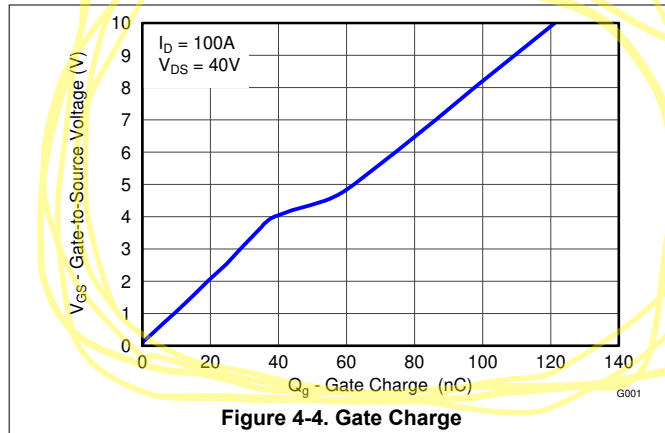


Figure 4-3. Transfer Characteristics

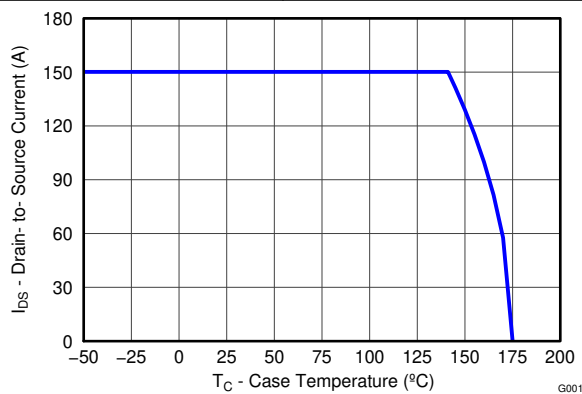
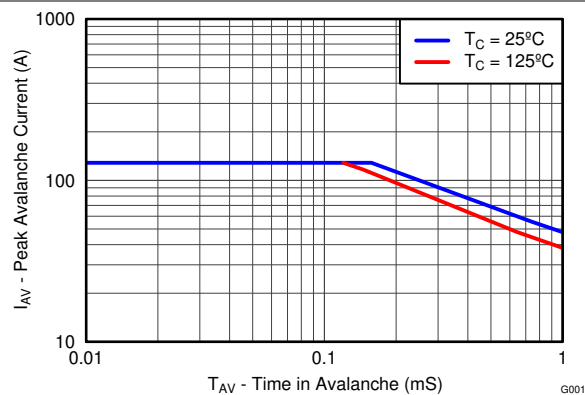
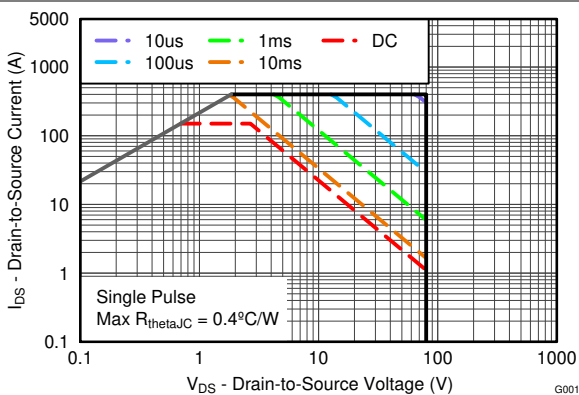
4.3 Typical MOSFET Characteristics (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)



4.3 Typical MOSFET Characteristics (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)



5 Device and Documentation Support

5.1 Third-Party Products Disclaimer

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To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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5.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (October 2014) to Revision C (May 2024) Page

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1

Changes from Revision A (February 2014) to Revision B (October 2014) Page

- Changed Pulsed Drain Current Conditions 1
- Updated the SOA in [Figure 4-10](#) 4

Changes from Revision * (December 2013) to Revision A (February 2014) Page

- Increased Package Current Limit to 150A 1
- Increased Pulsed Drain Current to 400A 1
- Updated SOA Curve 4

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD19506KCS	ACTIVE	TO-220	KCS	3	50	RoHS-Exempt & Green	SN	N / A for Pkg Type	-55 to 175	CSD19506KCS	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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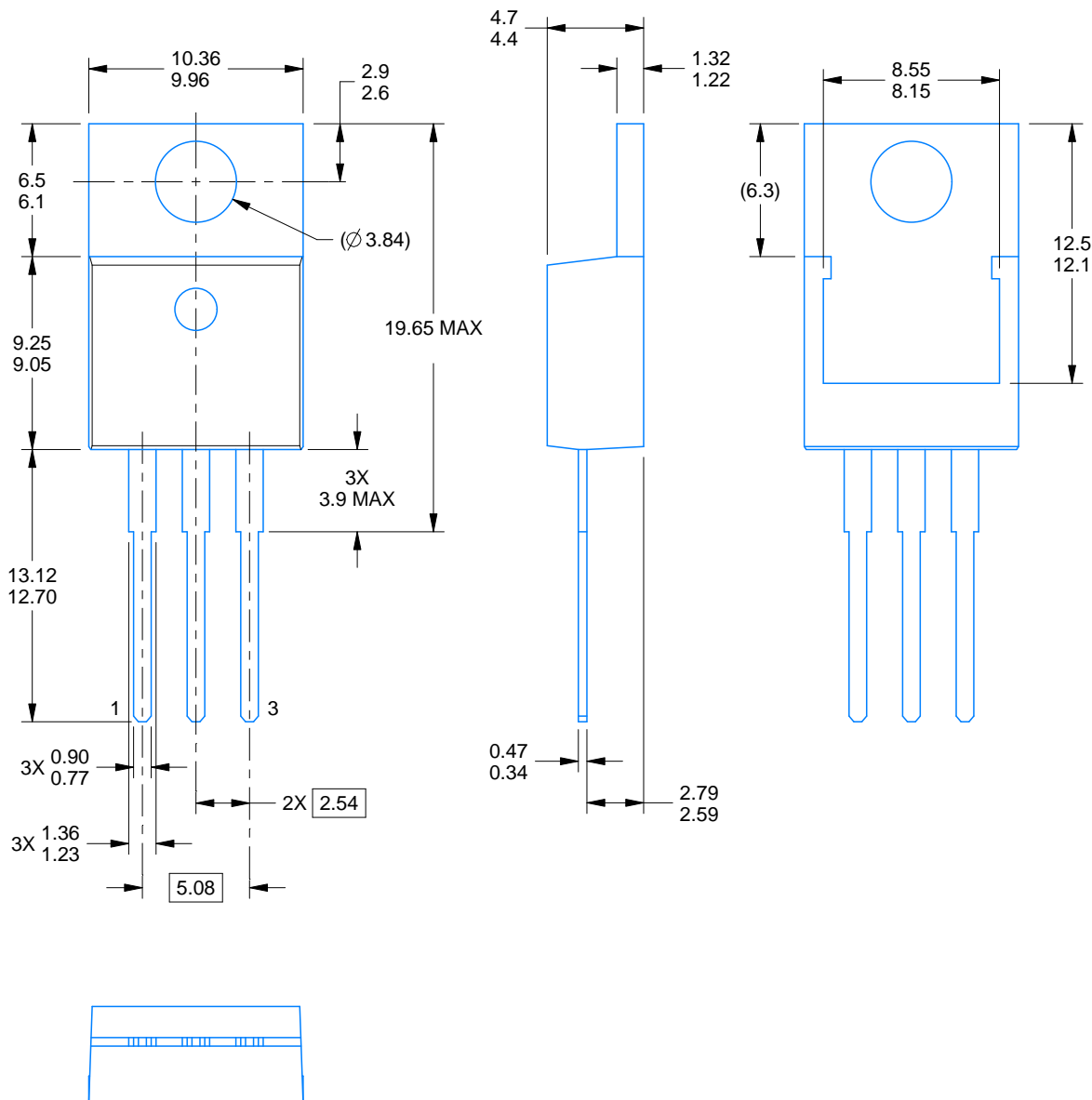
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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CSD19506KCS	KCS	TO-220	3	50	532	34.1	700	9.6
CSD19506KCS	KCS	TO-220	3	50	534.5	33	7000	3.4



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NOTES:

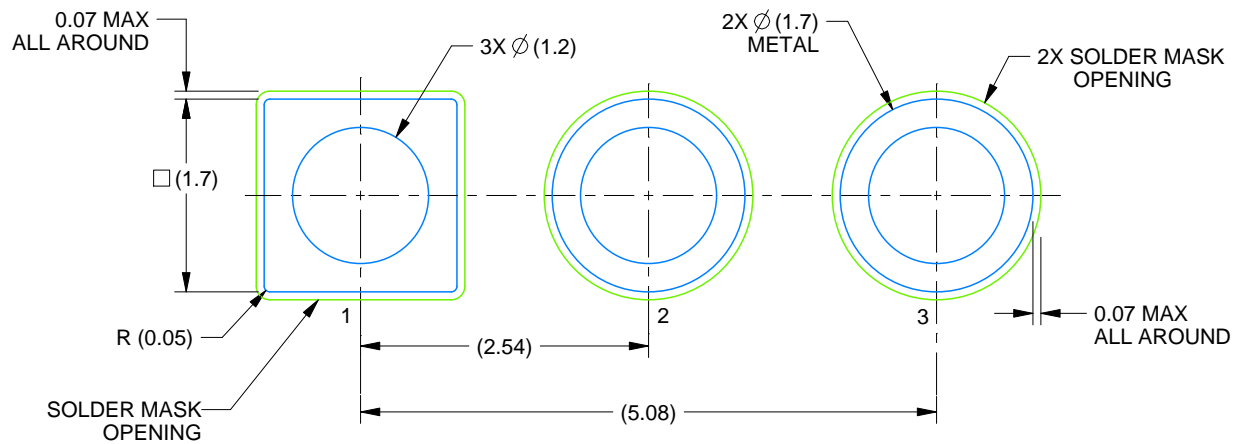
1. Dimensions are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-220.

EXAMPLE BOARD LAYOUT

KCS0003B

TO-220 - 19.65 mm max height

TO-220



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:15X

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